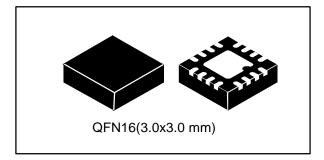
STOD32A



300 mA triple DC-DC converter for powering AMOLED displays

Data brief



Features

- Operating input voltage range from 2.5 V to 4.5 V
- 300 mA output current for step-up and inverting converters (V_{IN}> 2.9 V)
- 55 mA output current for an auxiliary step-up converter (V_{IN}> 2.9 V)
- 4.6 V positive step-up converter
- Programmable negative voltage from 0.8 V to - 4.8 V default -4.0 V
- Auxiliary step-up converter positive voltage programmable step from 5.8 V to 7.9 V default 7.6 V
- Soft-start with inrush current protection

- Overtemperature protection
- True-shutdown mode
- Short-circuit protection
- Package QFN16 (3.0x3.0 mm), 0.5 mm pitch

Applications

- Active matrix OLED power supply in portable devices
- Cellular phones, multimedia players, camcorders and digital still cameras

Description

The STOD32A is a triple DC-DC converter for AMOLED display panels. It integrates 300 mA step-up and inverting DC-DC converters plus auxiliary step-up converter. This device is particularly suitable for battery operated products, in which the major concern is overall system efficiency. Output voltages can be programmed by a dedicated pin, which implements Swire protocol. Soft-start with controlled inrush current limit, thermal shutdown and short-circuit protection are integrated functions of the device.

Table 1: Device summary

Order code	Positive voltage	Negative voltage	Auxiliary positive voltage	Package	Packing
STOD32ATPQR	4.6 V	-0.8 to 4.8 V	5.8 to 7.9 V	QFN16 (3x3 mm)	3000 samples per reel

Contents STOD32A

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1 Application schematic

Figure 1: Application schematic

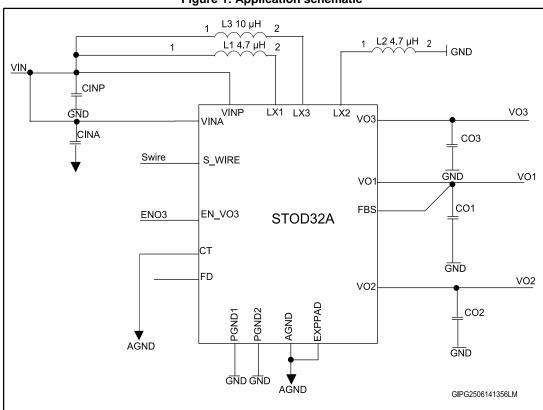


Table 2: Typical external components

Component	Manufacturer	Value	Size
L ₁ , L ₂ , L ₃	TOKO ALPS COILCRAFT	4.7 µH	2.5x2.0x1.2 2.5x2.0x1.2 4.0x4.0x1.2
CINA, CINP, CO2, CO3	MURATA SEMCO	22 μF 10 μF	0805 0402 0603

Package information STOD32A

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

3 QFN16 (3.0x3.0 mm) package information

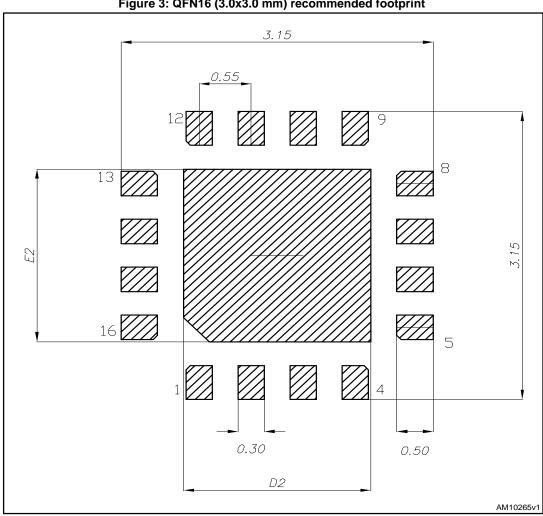
SEATING PLANE ppp A3 D PIN #1 ID D1 R=0.20 13 16 12 E2 F^{I} 9 8 5 b D2 7185330_G

Figure 2: QFN16 (3.0x3.0 mm) package outline

Table 3: QFN16 (3.0x3.0 mm) package mechanical data

Dim	mm			
Dim.	Min.	Тур.	Max.	
A	0.50	0.55	0.60	
A1	0.00	0.02	0.05	
b	0.20	0.25	0.30	
D	2.9	3.00	3.1	
D2	1.55	1.70	1.80	
E	2.9	3.00	3.1	
E2	1.55	1.70	1.80	
е		0.50		
L	0.20	0.30	0.40	

Figure 3: QFN16 (3.0x3.0 mm) recommended footprint





All dimensions are in mm

STOD32A Revision history

4 Revision history

Table 4: Document revision history

Date	Revision	Changes
16-Jul-2014	1	Initial release.
03-Nov-2015	2	Updated Table 3: "QFN16 (3.0x3.0 mm) package mechanical data".

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